

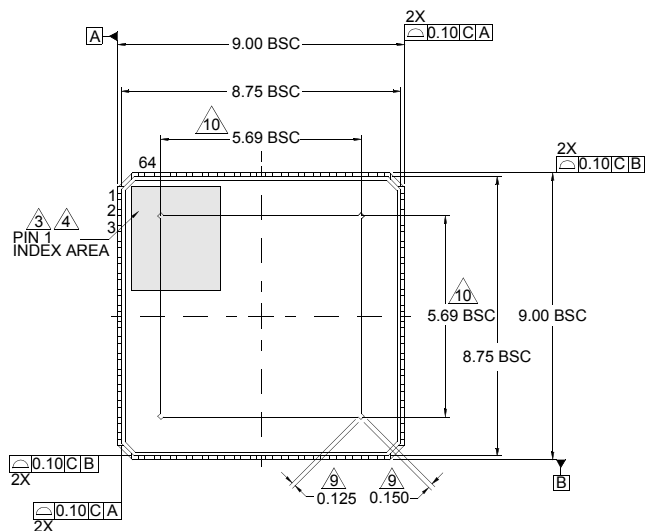
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

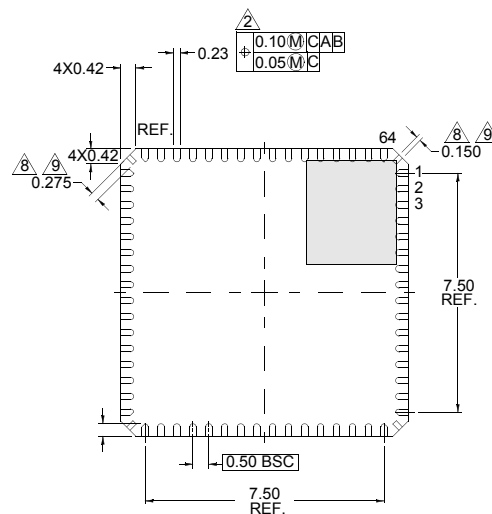
### L64.9x9A

64 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE WITH TOP EXPOSED PAD (QFN-TEP)

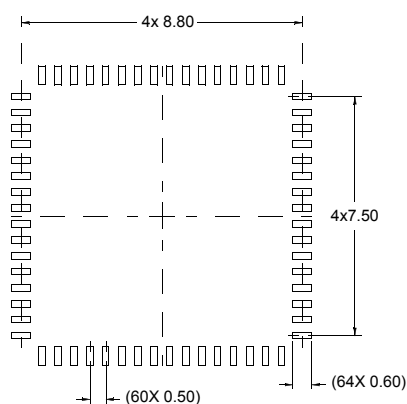
Rev 0, 6/09



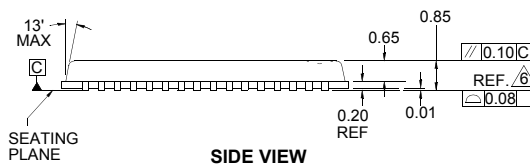
**TOP VIEW**



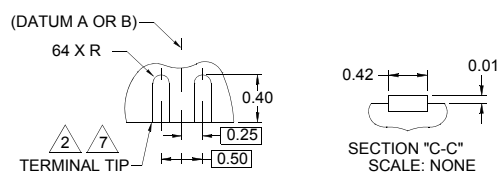
**BOTTOM VIEW**



**TYPICAL RECOMMENDED LAND PATTERN**



**SIDE VIEW**



#### NOTES:

1. Dimensioning & tolerancing conform to ASME Y14.5M-1994.
2. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30mm from terminal tip.
3. The pin #1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.
4. Exact shape and size of this feature is optional.
5. All dimensions are in millimeters.
6. Bilateral coplanarity zone applies to the exposed pad as well as the terminals.
7. Applied only for terminals.
8. The shape shown on four corners are not actual I/O.
9. R, T or S, U applies only for straight tiebar shapes. Any mold flash on the exposed tiebar area shall be allowable.
10. D2, E2 dimensions : Nominal exposed pad size.